Layer Stack Up Detail for: TIDA-00231.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
L2_GND-PLANE	(.G1)	1.4mil	FR-4
L3_PWR-PLANE	(.G2)	1.4mil	FR-4
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
3780MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7.87 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.152mm (6MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[X] FR-408 [ ] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER

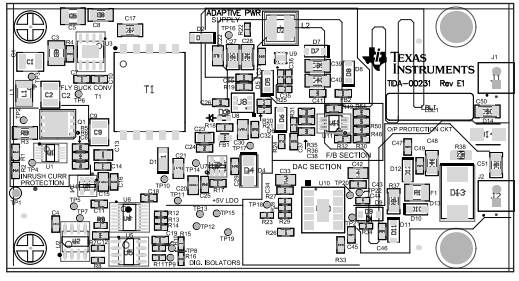
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES [X] NO [ ]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED
ASSEMBLY VARIANT: [No Variations]

1000 (mil)

ALL DIMENSIONS ARE IN MILS	BOARD #: TIDA-00231	REV: E1	SUN REC: Not in Version Control
LAYER NAME = Top Overlay Top Scope			
PLOT NAME = Top Assembly Drawing	GENERATED : 12/07/2014 4:35:23 PM	TEXAS INSTRUMENTS	

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

TEXAS INSTRUMENTS

PROJECT TITLE: Adaptive Power Supply for DAC
DESIGNED FOR: Public Release
FILE NAME: TIDA-00231
ENGINEER: Amol Gadkari
LAYOUT BY: Sharanu
SCALE: 1.00
ALTIUM DESIGNER VERSION: 10.0.0.27009

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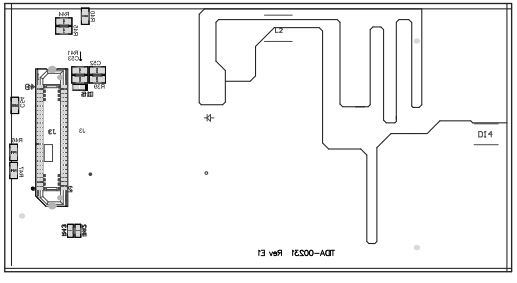
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [X] NO [ ]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



1000 (mil)

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ASSEMBLY VARIANT: [No Variations]

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